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HEET

HITA.0376

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof. 2. Name and Address of Receiving Party(ies):

Name of Conveying Party(ies):

Takashi SATOU, Shigezumi MATSUI, Peter LEE and Gouichi YOKOMIZO

Additional names of conveying parties attached:

Yes

Hitachi, Ltd. Name:

Address: 6, Kanda Surugadai 4-chome

Chiyoda-ku, Tokyo, Japan

Nature of Conveyance:

Assignment

Merger

Security Agreement

Change of Name

Other:

Execution Date:

March 26, 2003

(a) Patent Application Number(s):

If this document is being filed together with a new application, the execution date of the application is:

Additional Numbers Attached.

5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:

Name:

Stanley P. Fisher

Address:

Reed Smith LLP

3110 Fairview Park Dr.

Suite 1400

Falls Church, Va. 22042

(b) Patent Numbers:

10416709

Total Number of Applications and Patents Involved: 1

Total Fee:

\$40.00

(37 C.F.R. § 3.41)

× Enclosed.

Ø Authorized to be charged to deposit account.

Deposit Account Number: 08-1480

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Statement and Signature:

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

Registration No. 34,072

Stanley P. Fisher, Registration No. 24, 344

Total number of pages comprising cover sheet: 1

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PATENT REEL: 014525 FRAME: 0916

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd.,

a corporation organized under the laws of Japan,

located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,

its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT AND DATA PROCESSING SUSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi, Ltd.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

RECORDED: 05/14/2003

INIVENITOR(C)

	(発明者フルネームサイン)	(署名日)
1)	Talcashi Satou Takashi SATOU	26/March / 2003
2)	Shigezumi Matzushigezumi MATSUI	26/Harch /2003
3)	Peter LEE	26/March/2003
4)	Louidi Yokomiya Gouichi YOKOMIZO	26/March/2003
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PATENT REEL: 014525 FRAME: 0917

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